

**APPLICATION  
FOR  
UNITED STATES LETTERS PATENT**

**Applicant:**

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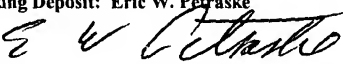
**For:**

**“Self-aligned Double-Gate Process by Self-aligned  
Oxidation”**

**Docket: YOR920020233US1**

**INTERNATIONAL BUSINESS  
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1 Self-aligned Planar Double-Gate Process  
2 by Self-aligned Oxidation

3 TECHNICAL FIELD

4 The field of the invention is that of forming dual-gate transistors in  
5 integrated circuit processing, in particular self-aligned dual gate transistors.

6 BACKGROUND OF THE INVENTION

7 Workers in the field of integrated circuits are constantly striving to reduce  
8 the size of devices, in particular transistors.

9 As FET dimensions are scaled down, it becomes increasingly difficult to  
10 control short-channel effects by conventional means. Short-channel effects  
11 well known to those skilled in the art are the decrease in threshold voltage  
12  $V_t$ , in short-channel devices, i.e. sub-0.1 micron, due to two-dimensional  
13 electrostatic charge sharing between the gate and the source/drain region.

14 An evolution beyond the standard single gate metal oxide semiconductor  
15 field effect transistor (MOSFET) is the double-gate MOSFET, in which the  
16 device channel is confined between top and bottom gate dielectric layers.

1 This structure, with a symmetrical gate structure, can be scaled to about half  
2 of the channel length as compared with a conventional single gate MOSFET  
3 structure. It is well known that a dual gate or double-gate MOSFET device  
4 has several advantages over conventional single gate MOSFET devices.  
5 Specifically, the advantages over conventional single gate counterparts  
6 include: a higher transconductance, and improved short-channel effects.

7 For instance, Monte Carlo simulation has been carried out on a 30nm  
8 channel dual-gate MOSFET device and has shown that the dual gate device  
9 has a very high transconductance (2300mS/nm) and fast switching speeds  
10 (1.1ps for nMOSFET).

11 Moreover, improved short channel characteristics are obtained down to  
12 20nm channel length with no doping needed in the channel region. This  
13 circumvents the tunneling breakdown, dopant quantization, and dopant  
14 depletion problems associated with channel doping that are normally present  
15 with single gate MOSFET devices.

16 Currently, both vertical and horizontal gate structures are actively being  
17 pursued by many workers in the field. The horizontal gate structure has  
18 several advantages over the vertical structures due to the similarity of current  
19 state of the art CMOS devices. However, one major and formidable  
20 challenge of fabricating the double gate is aligning the bottom gate to the top  
21 gate.

1     SUMMARY OF THE INVENTION

2     The invention relates to an integrated circuit having dual-gate transistors.

3     An aspect of the invention is the formation of a self-aligned back gate by  
4     oxidizing a portion of the back gate electrode layer using the front gate as an  
5     oxidation mask.

6     Another aspect of the invention is the implantation at the outer edges of the  
7     structure of a species that promotes oxidation.

8     Another aspect of the invention is the oxidation for a sufficient time and  
9     temperature to reduce stress in the transistor body.

10    Another aspect of the invention is the transverse extent of the oxidation to  
11    extend the boundary of the back gate below the edge of the transistor body.

12    Another aspect of the invention is the formation of raised source and drain  
13    structures within a space left by the spacers that define the width of the  
14    transistor body.

15    BRIEF DESCRIPTION OF THE DRAWINGS

16    Figures 1A and 1B show steps in the formation of the original unpatterned

1 structure.

2 Figure 2 shows a front gate electrode.

3 Figure 3 shows the formation of a first pair of spacers defining the transistor  
4 body.

5

6 Figure 4 shows the result of etching the SOI layer to define the transistor  
7 body.

8 Figure 5 shows the formation of a second pair of spacers that protect the  
9 transistor body during oxidation.

10 Figure 6 shows the result of the oxidation that defines the width of the back  
11 gate electrode.

12 Figure 7 shows the result of depositing dielectric enclosing the transistor  
13 structure.

14 Figure 8 shows the result of stripping the spacers to form an aperture holding  
15 the raised S/D structures.

16 Figure 9 shows the raised S/D contacts with isolating dielectric to insulate  
17 the S/D contacts.

1     DETAILED DESCRIPTION

2     Figure 1A shows an initial SOI wafer having bulk substrate 105, with buried  
3     oxide (BOX) 107 separating the bulk substrate from the single-crystal silicon  
4     SOI layer 4 that will become the transistor body. Layer 4 has a nominal  
5     thickness that may range from 2nm to 50nm.

6     A layer of thermal oxide 3 that will become the back gate dielectric is grown  
7     on silicon layer 4 to a thickness of 1nm to 3nm and a layer of polycrystalline  
8     silicon (poly) 2 is deposited by CVD in the range of 100nm to 400nm that  
9     will become the back gate electrode. Layer 3 may be composed of  
10    oxynitride or may be nitridized as a design choice, so long as it is suitable for  
11    a gate dielectric.

12    Figure 1B shows the result of bonding a second, bulk wafer to the first one  
13    and removing substrate 105, e.g. by grinding and BOX layer 7, e.g. by  
14    etching in dilute hydrofluoric acid. The new substrate is denoted with the  
15    numeral 1 in Figure 1B.

16    Layer 4 is oxidized again with a thermal oxide 5 that will become the front  
17    gate dielectric. Layer 5 may also be oxynitride or may be nitridized. It may  
18    also optionally be a high dielectric material such as ZrO<sub>2</sub>, HfO<sub>2</sub>, AlO<sub>2</sub> or  
19    other conventional high-k material. Another poly layer 6 is deposited by  
20    CVD, preferably in the range of 70nm to 250nm in thickness.

1 Figure 2 shows the result of depositing on poly layer 6 a pair of first and  
2 second pattern transfer layers, illustratively layer 7a of 10nm to 70nm of  
3 oxide ( $\text{SiO}_2$ ) and layer 7b of 10nm to 70nm of nitride ( $\text{Si}_3\text{N}_4$ ). A layer of  
4 photoresist is deposited and patterned to define the front gate. The pattern  
5 transfer layers are etched to define a hardmask and the resist is stripped.  
6 Poly layer 6 is etched using the hardmask as a pattern to form first (front)  
7 gate 8.

8 Figure 3 shows the result of depositing and defining layers that will protect  
9 first gate 8 during the formation of the second or back gate. A conformal  
10 oxide layer 9 is deposited, illustratively of CVD TEOS 2nm to 10nm in  
11 thickness. Next, a CVD nitride film 10nm to 100nm thick is deposited. The  
12 nitride film is etched in a conventional directional etch to remove the film on  
13 horizontal surfaces to form nitride spacers 10, stopping the etch on oxide  
14 film 9.

15 Figure 4 shows the result of performing another directional etch on layer 9  
16 and gate layer 5, e.g. with HBr chemistry and a directional etch that removes  
17 silicon selectively to oxide ( e.g. HBr chemistry) to etch through layer 4,  
18 stopping on layer 3. The preceding directional etches are conventional and  
19 generically described as reactive ion etches.

20 The result is that the transistor body has been defined to extend past the first  
21 gate electrode on both the left and right in the figure by the thickness of  
22 spacers 9 and 10. Spacers 9 and 10 will be referred to as being in proximity

1 to the gate and to the vertical edge of the transistor body, meaning that they  
2 are close to the referenced structure but not necessarily directly in contact  
3 with it. Additional liners may be deposited as an etch stop or as an insulator  
4 to remain in the final structure. The vertical edge of the transistor body is  
5 denoted with numeral 11 in this figure and will be contacted by additional  
6 silicon added in a later stage. The thickness of the transistor body  
7 perpendicular to the plane of the paper will be set according to the designed  
8 current capacity of the transistor, as is conventional.

9 Optionally, an extra space may be allowed in front of or behind the plane of  
10 the paper to make contact with the lower gate electrode that will be formed  
11 from layer 2.

12  
13 Figure 5 shows the result of depositing a conformal layer of CVD nitride and  
14 etching it directionally to form spacers 12 that protect the vertical edge of the  
15 transistor body and also define the boundary of the area in layer 2 that will  
16 be oxidized in the following step.

17 Illustratively, as shown in Figure 6, the thickness of spacers 10 and 12 are set  
18 to facilitate the following oxidation step, in which layer 2 is oxidized  
19 through oxide layer 3, so that only the central unoxidized portion functions  
20 as the back gate electrode.

21 Those skilled in the art would not think to exploit the transverse growth of  
22 oxide to penetrate under the transistor body because the expansion in volume



1 of the oxide compared with silicon would have been though to delaminate or  
2 to exert undesired stress on the transistor body.

3 Advantageously, it has been found that the transverse oxide growth is rapid  
4 enough in the poly layer 2 that the resulting stress is acceptable. In addition,  
5 it has been found that if the oxidation is performed at a temperature of about  
6 1000C or greater for a time of about 20 min or greater, that the stress caused  
7 by the oxidation is relaxed since the SiO<sub>2</sub> is more viscous under these  
8 conditions.

9 The parameters of the oxidation step are adjusted empirically to provide for  
10 the correct amount of sideways growth. Optionally, an angled ion implant of  
11 phosphorus or other oxide-promoting species, indicated schematically by  
12 arrows 123 in Figure 5 and by shaded area 125, can be used prior to the  
13 oxidation to facilitate and control the lateral oxidation extent. The angle  
14 with respect to the wafer normal will depend on the height and spacing of  
15 nearby structures. The dose and voltage will be set empirically. Greater  
16 lateral penetration can be achieved by increasing the voltage.

17 Alternatively, or additionally, a nitrogen (or other oxide-retarding species)  
18 implant, indicated schematically by arrows 127 and shaded area 128 in Figur  
19 5, may be performed at a normal incidence angle. The back gate electrode  
20 with a sufficient amount of nitrogen incorporation will retard the oxidation  
21 in the vertical direction thereby enabling more control and flexibility over  
22 the vertical to lateral oxidation extent. The voltage can be set to leave a light

1 dose near the top of layer 2 and a retarding dose in the lower portion.

2 The oxide penetrates a nominal 30-70nm sideways toward the central portion  
3 and a nominal 30-70nm downward.

4 Figure 7 shows the result of depositing a CVD oxide film 14 to a thickness  
5 nominally greater than the height of the gate stack (plus layers 7a and 7b),  
6 that is then planarized, e.g. in a chemical-mechanical polishing (CMP)  
7 process.

8 After planarization, the oxide is recessed to a height less than the height of  
9 the gate stack (and greater than the height of gate 8).

10 Figure 8 shows the result of stripping the spacers 10 and 12 and cap 7b, e.g.  
11 in hot phosphoric acid, to open an aperture 25 for the raised source-/drain  
12 structures. Another nitride spacer 15, having a nominal thickness of  
13 10-70nm, is formed on the vertical surfaces of the aperture to isolate the S/D  
14 contacts from the gate. An implant of conventional magnitude for the S/D  
15 may be performed in aperture 25 at this time. The completion of the S/D,  
16 whether at this time or after the raised S/D step shown in Figure 9, completes  
17 the transistor.

18 A conventional cleaning step (preferably wet cleaning) removes any residue  
19 from vertical surfaces 11 of the transistor body to make a good contact  
20 between the body and the raised S/D structures.

1 Figure 9 shows the result of filling aperture 25 with silicon 16 - by selective  
2 epitaxy, or by deposition of amorphous silicon or poly (with or without a S/D  
3 implant). A planarization, e.g. CMP followed by a dry etch to recess the  
4 silicon results in the structure shown, in which apertures 27 are prepared for  
5 the deposition of a conventional interconnect to connect transistors to form  
6 the circuit.

7 Conventional middle of the line and back of the line steps are performed to  
8 complete the circuit, referred to for convenience as completing the circuit.

9 The layers that form gate electrodes 2 and 8 are put down with conventional  
10 dopant concentrations (or implanted later) sufficient to provide the proper  
11 conductivity for the gates. Similarly, the raised S/D structures have the  
12 proper amount of dopant added during deposition.

13 Layer 4 that forms the transistor body may have a conventional dopant  
14 concentration. Those skilled in the art are aware of the type and  
15 concentration of dopants to form NFETs and PFETs.

- 1 Process Flow
- 2 Initial Wafer Preparation
- 3 Start with SOI wafer with silicon SOI layer
- 4 Thermal oxide for back gate dielectric
- 5 Poly for back gate electrode
- 6 Bond Carrier Wafer
- 7 Remove initial substrate
- 8 Remove initial BOX
- 9 Front gate dielectric
- 10 Front gate electrode
- 11 Gate Patterning
- 12 Pattern transfer layer 1 (oxide)
- 13 Pattern transfer layer 2 (nitride)
- 14 Pattern front gate
- 15 First Spacer Formation
- 16 Deposit Etch stop layer
- 17 Deposit Spacer layer
- 18 Directional etch to form spacers
- 19 Channel Patterning
- 20 Etch pattern transfer layer 1
- 21 Etch channel, stopping on back oxide
- 22 Second Spacer Formation

1           Deposit spacer material  
2           Define spacers  
3    Define Self-Aligned Back Gate  
4           Oxidize Back Gate Layer, extending oxidation horizontally to define  
5    self-aligned gate  
6    Deposit Thick dielectric, planarize  
7    Remove First and Second Spacers  
8    Gate Isolation Spacers  
9    S/D Contact Deposition

10   While the invention has been described in terms of a single preferred  
11   embodiment, those skilled in the art will recognize that the invention can be  
12   practiced in various versions within the spirit and scope of the following  
13   claims.